TAZMO

Q2 FY2026 Financial Announcement

April 2026 – June 2026

August 10, 2026

Security Code: 6266

Company Guide

https://tazmo.co.jp/wp/wp-content/uploads/2025/11/company%20guide.pdf

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Q2 FY2026 Consolidated Financial Summary

Q2 FY2026 Financial Highlights

TAZMO

Net sales	Operating income	Ordinary income	Net income(*)
12,684 Million Yen	**123** Million Yen	**270** Million Yen	**35** Million Yen
YoY Change △24.4%	YoY Change △95.1%	YoY Change △88.6%	YoY Change △97.8%

Overview

- Both sales and profit declined year on year. Net sales fell short of the plan in the Semiconductor Equipment, Transfer Equipment and Surface Treatment Equipment Businesses.
- Profit also fell well short of the plan, reflecting the lower net sales, valuation losses on equipment not yet inspected and accepted, and provisions for additional costs identified on certain equipment.
- Order intake grew substantially in the Semiconductor Equipment, Transfer Equipment and Surface Treatment Equipment Businesses, marking record highs on both a quarterly and a cumulative basis.

(*) Net income: Net income attributable to owners of parent

Q2 FY2026 Financial Summary

TAZMO

Net sales fell short of the plan, mainly due to delays in inspection and acceptance in the Semiconductor Equipment and Surface Treatment Equipment Businesses. Profit also fell well short of the plan, reflecting the lower net sales, valuation losses on equipment not yet inspected and accepted, and the recognition of additional costs.

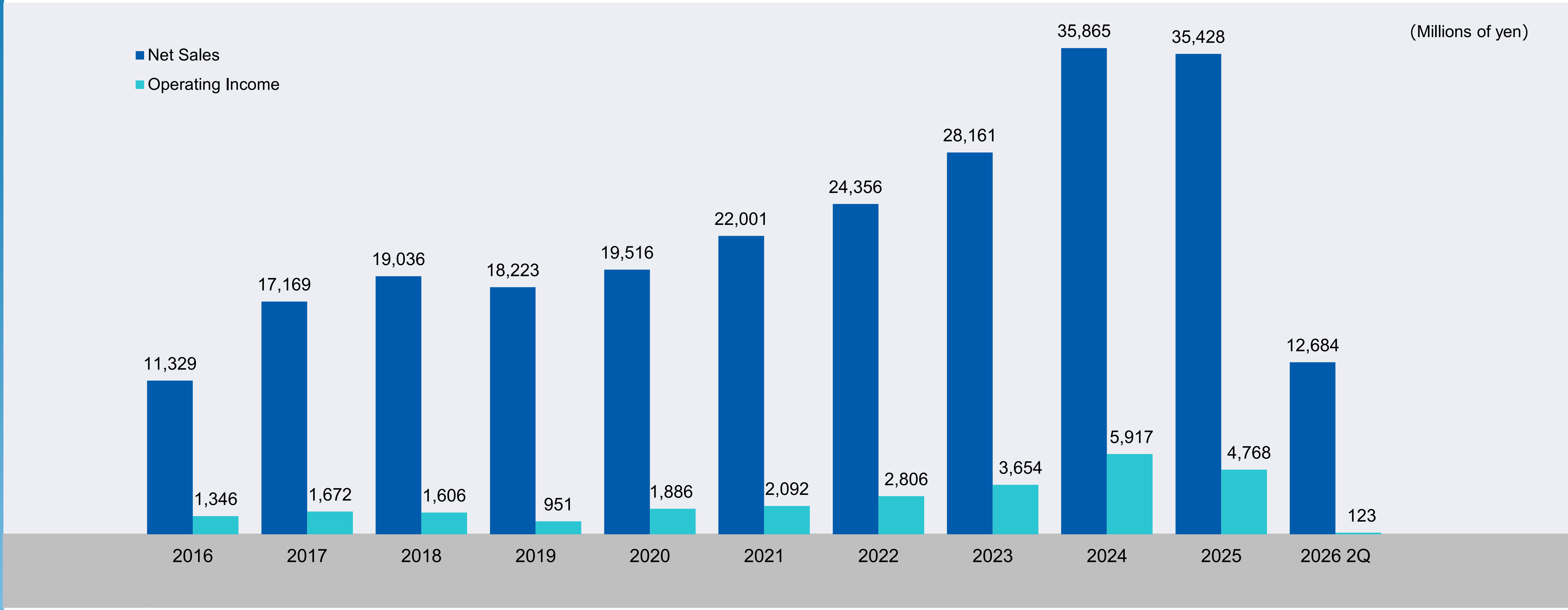
(Millions of yen)	Q2 FY2025 Actual	Q2 FY2026		YoY change (%)
		Actual	Net sales ratio (%)	
Net sales	16,787	12,684	-	△24.4
Gross profit	5,231	3,598	28.4	△31.2
Operating income	2,517	123	1.0	△95.1
Ordinary income	2,384	270	2.1	△88.6
Net income attributable to owners of parent	1,645	35	0.3	△97.8

	FY2026 Initial H1 Estimate	vs. Initial H1 Estimate (%)	FY2026 Full Year Estimate	vs. Full Year Estimate (%)
Net sales	15,570	81.5	35,500	35.7
Gross profit	-	-	-	-
Operating income	890	13.8	3,600	3.4
Ordinary income	800	33.9	3,500	7.7
Net income attributable to owners of parent	600	6.0	2,500	1.4

Trend in Net sales and Operating profit(Quarterly)

Trend in Net sales and Operating profit (Full year)

TAZMO



Balance Sheet

TAZMO

(Millions of yen)	FY2025 Actual	Q2 FY2026 Actual	YoY change(%)
Current assets	37,809	38,383	573
Non-current assets	9,083	10,136	1,053
Property, plant and equipment	7,812	8,876	1,063
Intangible assets	199	193	△5
Investments and other assets	1,070	1,066	△4
Total assets	**46,893**	**48,520**	**1,626**
Current Liabilities	14,393	15,892	1,499
Non-Current Liabilities	5,462	5,720	257
Total liabilities	**19,855**	**21,612**	**1,757**
Total net assets	**27,037**	**26,907**	**△130**
Equity ratio	56.6%	54.4%	△2.2P

Major Change

(Millions of yen)

Current Assets

Cash and deposits	△1,498
Notes and accounts receivable - trade	＋397
Inventories	＋1,545

Current Liabilities

Notes and accounts payable - trade	＋888
Electronically recorded obligations – operating	△1,478
Contract liabilities	＋2,557
Short-term borrowings	＋321
Income taxes payable	△676

Non-Current Liabilities

Long-term borrowings	+207

Cash Flow

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(Millions of yen)	Q2 FY2025 Actual	Q2 FY2026 Actual	YoY change(%)
Cash flow from operating activities	4,394	△336	△4,730
Cash flow from investing activities	△4,540	△290	4,249
Free cash flow	△145	△626	△480
Cash flow from financing activities	△556	7	564
Cash on hand	8,719	13,456	4,737

Highlights

(Millions of yen)

Cash flow from operating activities

Profit before income taxes	270
Contract Liabilities	2,401
Inventories	△1,676
Income taxes paid	△826

Cash flow from investing activities

Net increase in time deposits	1,056
Purchase of property, plant and equipment	△1,327

Cash flow from financing activities

Proceeds from long-term borrowings	2,000
Repayments of long-term borrowings	△1,640
Dividends paid	△497

Balance Sheet

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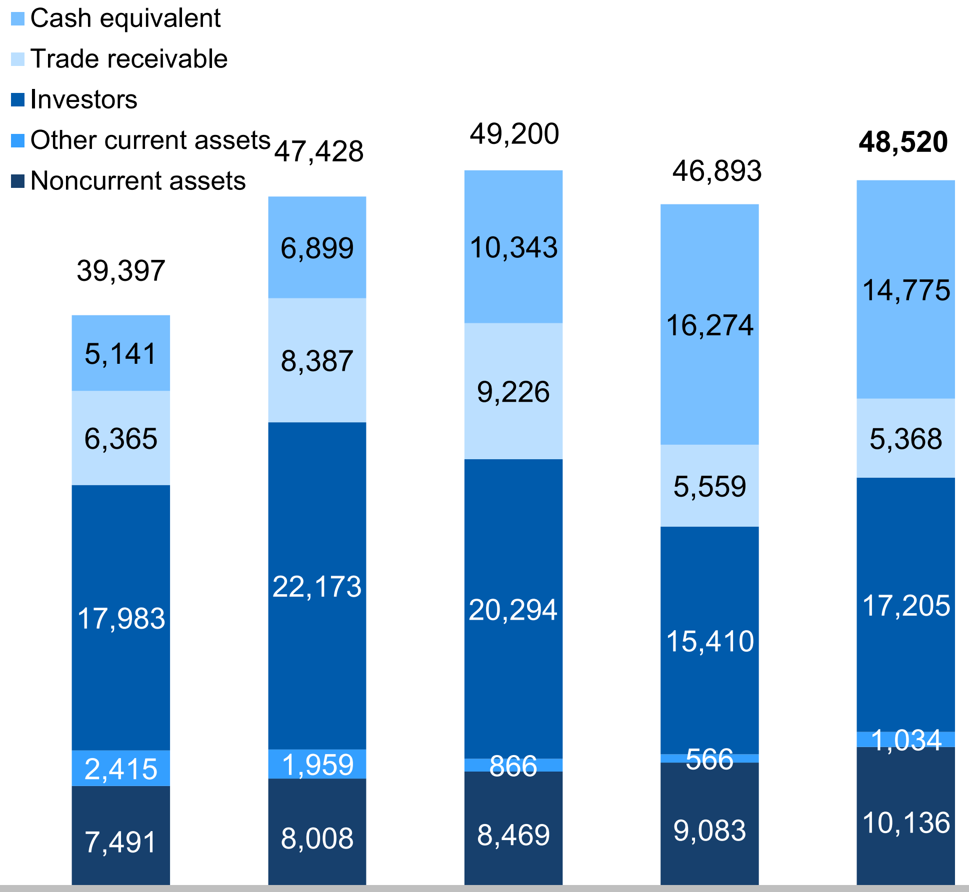
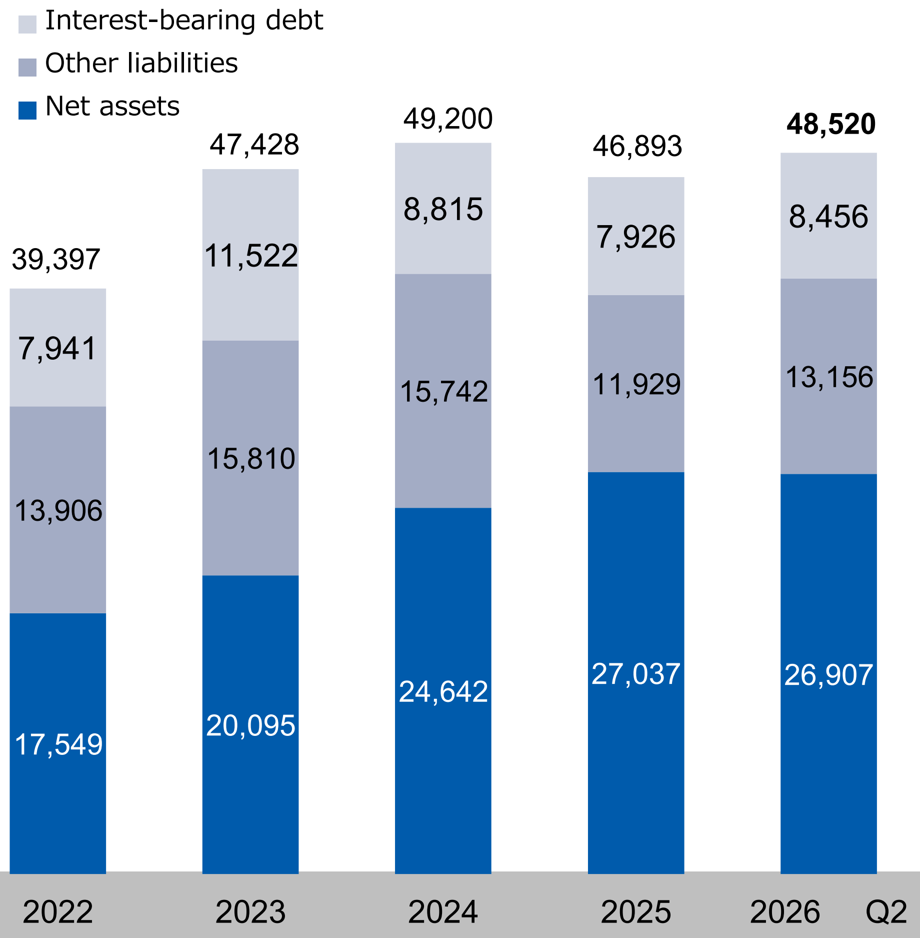
Assets

(Millions of yen)



Liabilities/Equity

(Millions of yen)



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Q2 FY2026 Segment Information

Net Sales and Operating Profit by Segment

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(Millions of yen)

Segment	Item	Q2 FY2025 Actual	Q2 FY2026 Actual	YoY(%)	FY2026 Initial H1 Estimate	vs. Initial H1 Estimate (%)	FY2026 Full Year Estimate	vs. Full Year Estimate (%)
Process equipment business	Net sales	12,193	10,668	△12.5	12,870	82.9	29,700	35.9
	Operating income	1,920	220	△88.5	900	24.5	3,400	6.5
■ Semiconductor equipment	Net sales	7,088	6,080	△14.2	-	-	18,500	32.9
■ Transfer equipment	Net sales	3,911	3,452	△11.7	-	-	8,860	39.0
■ Cleaning equipment	Net sales	1,194	1,135	△4.9	-	-	2,340	48.5
Precision molding dies and plastic moldings business	Net sales	606	563	△7.0	600	94.0	1,300	43.4
	Operating income	56	△2	-	30	-	70	-
Surface treatment equipment business	Net sales	3,987	1,452	△63.6	2,100	69.2	4,500	32.3
	Operating income	517	△89	-	△40	-	130	-
Elimination of inter-segment transactions	Operating income	24	△5	-	-	-	-	-
Total	Net sales	16,787	12,684	△24.4	15,570	81.5	35,500	35.7
	Operating income	2,517	123	△95.1	890	13.8	3,600	3.4

Trend in Net sales by Segment(Quarterly)

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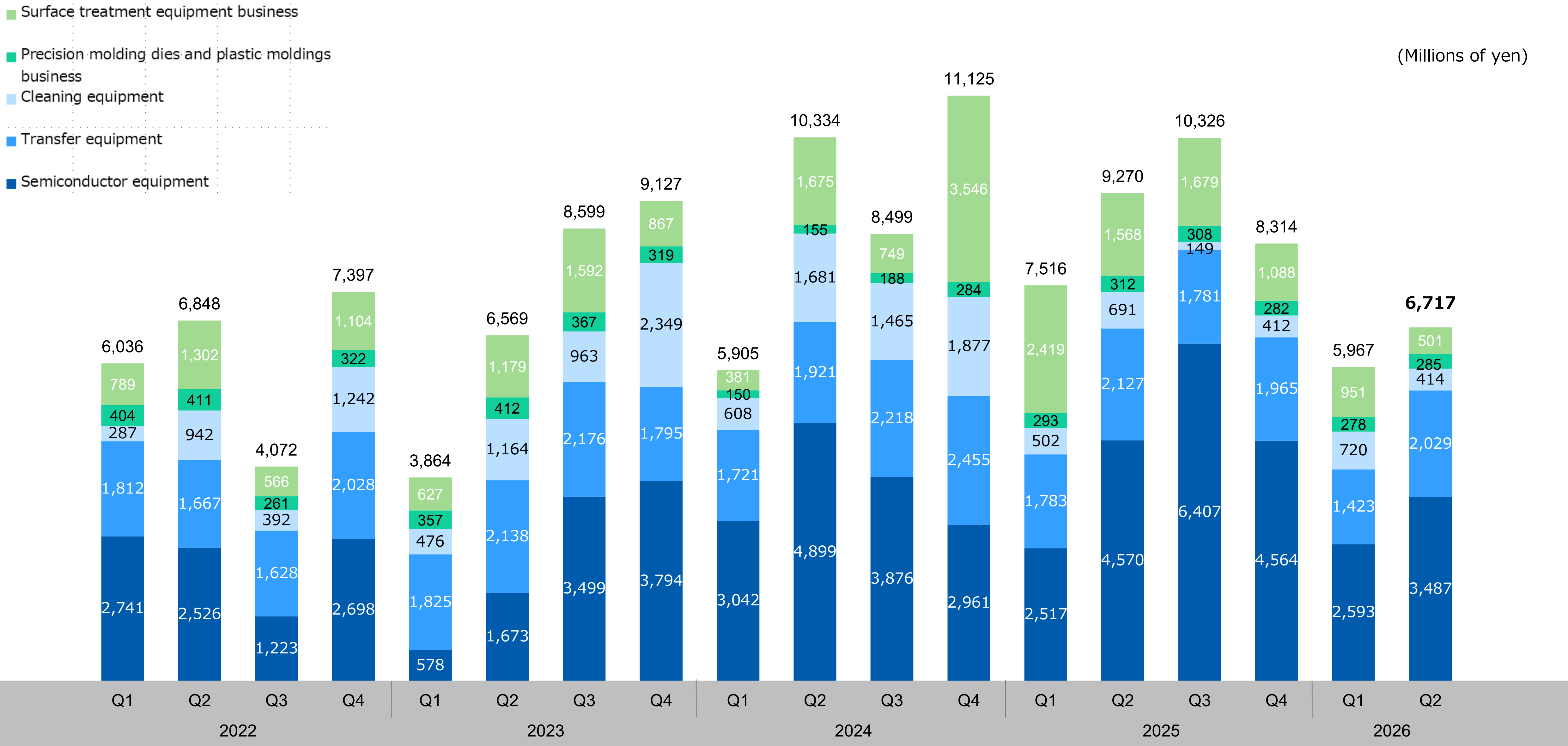
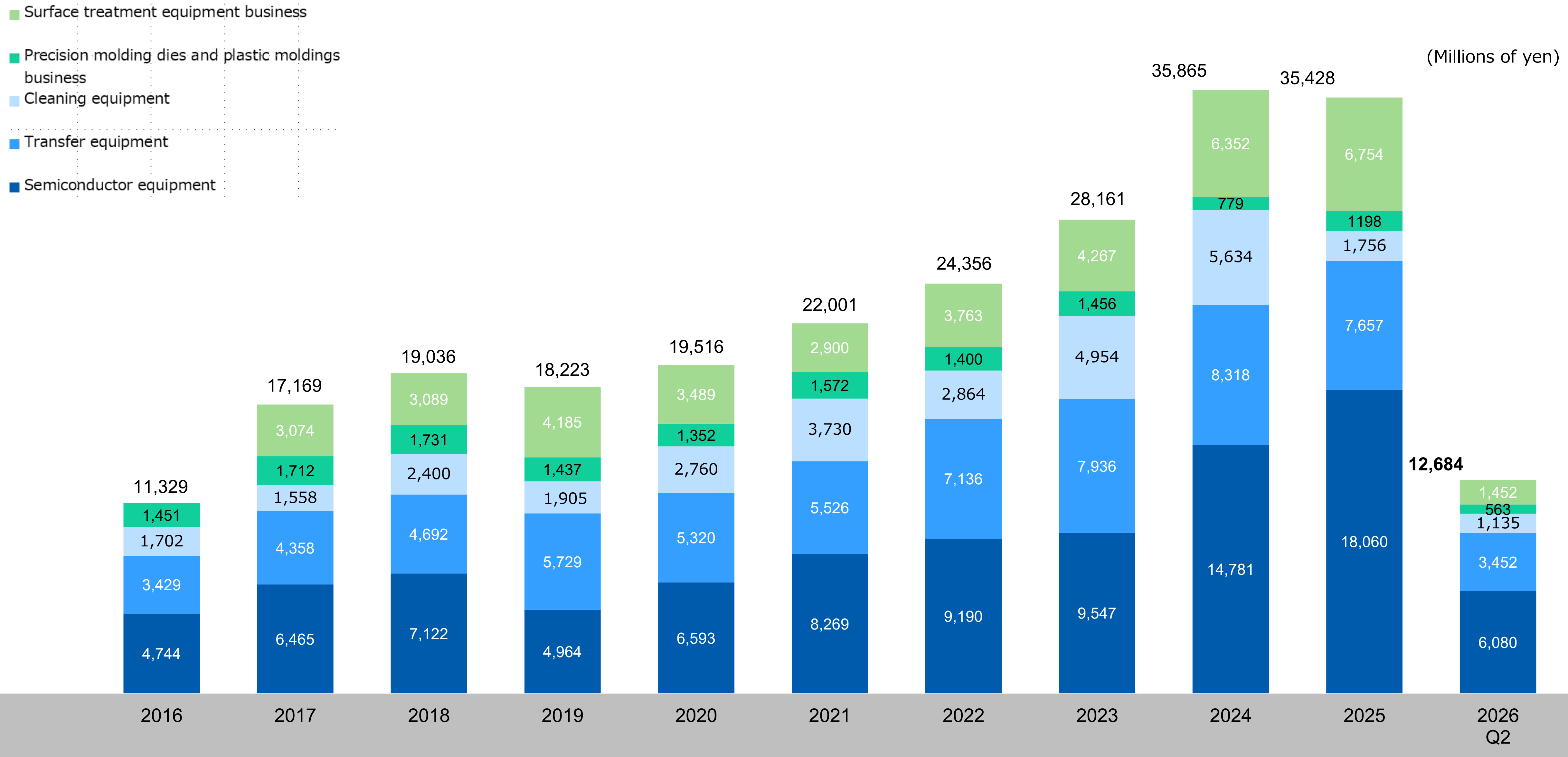


Starting from the fiscal year ending December 2026, the business previously recorded under the “Coater” segment has been reclassified and reported in combination with the “Semiconductor Equipment” segment. Accordingly, past performance figures have also been restated under the same segment classification. For sales trends under the previous classification, please refer to the supplementary materials

Trend in Net sales by Segment(Full year)

TAZMO



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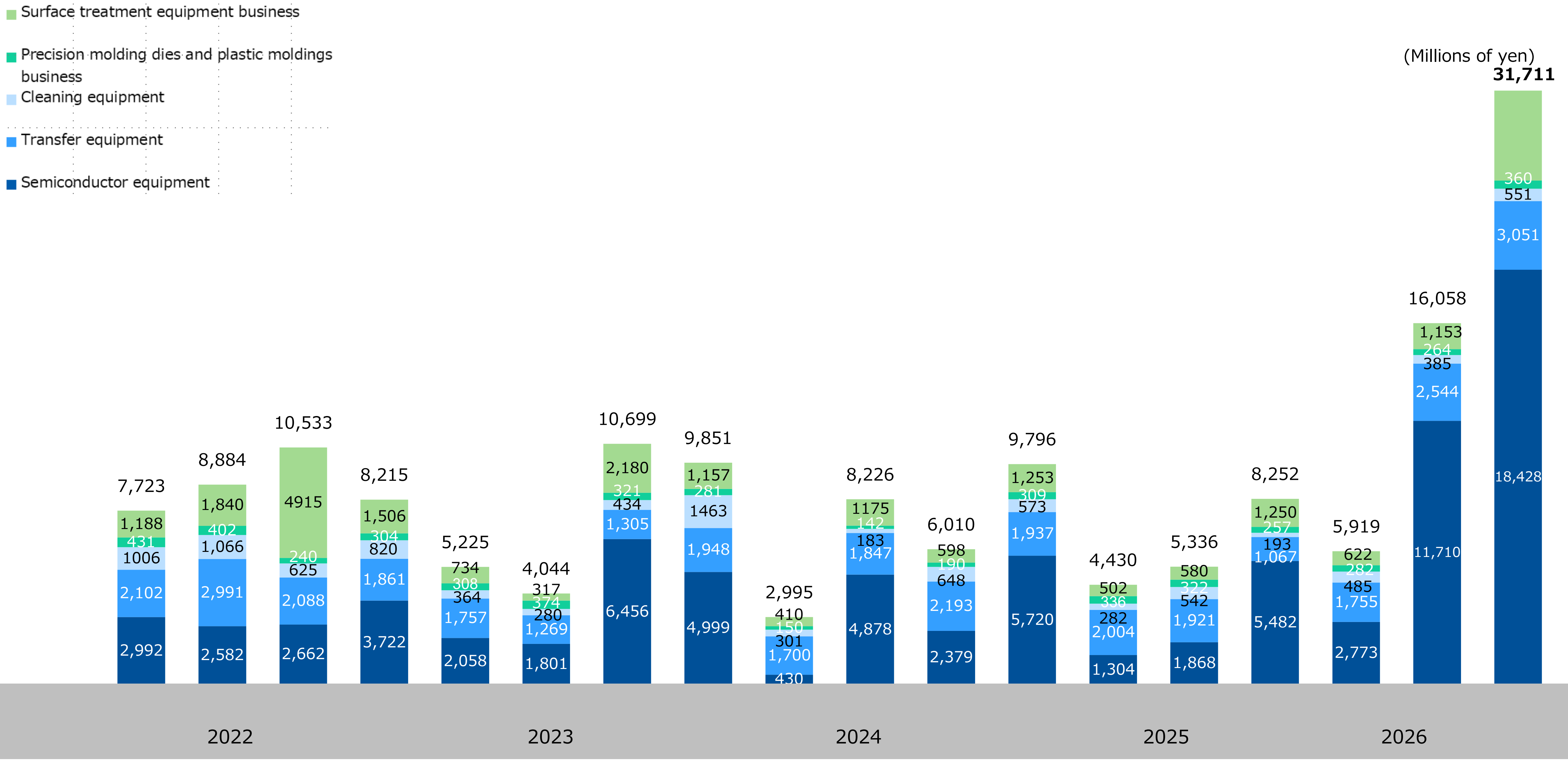
Trend in Sales Orders by Segment(Quarterly)

TAZMO



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Trend in Sales Orders by Segment(Full year)

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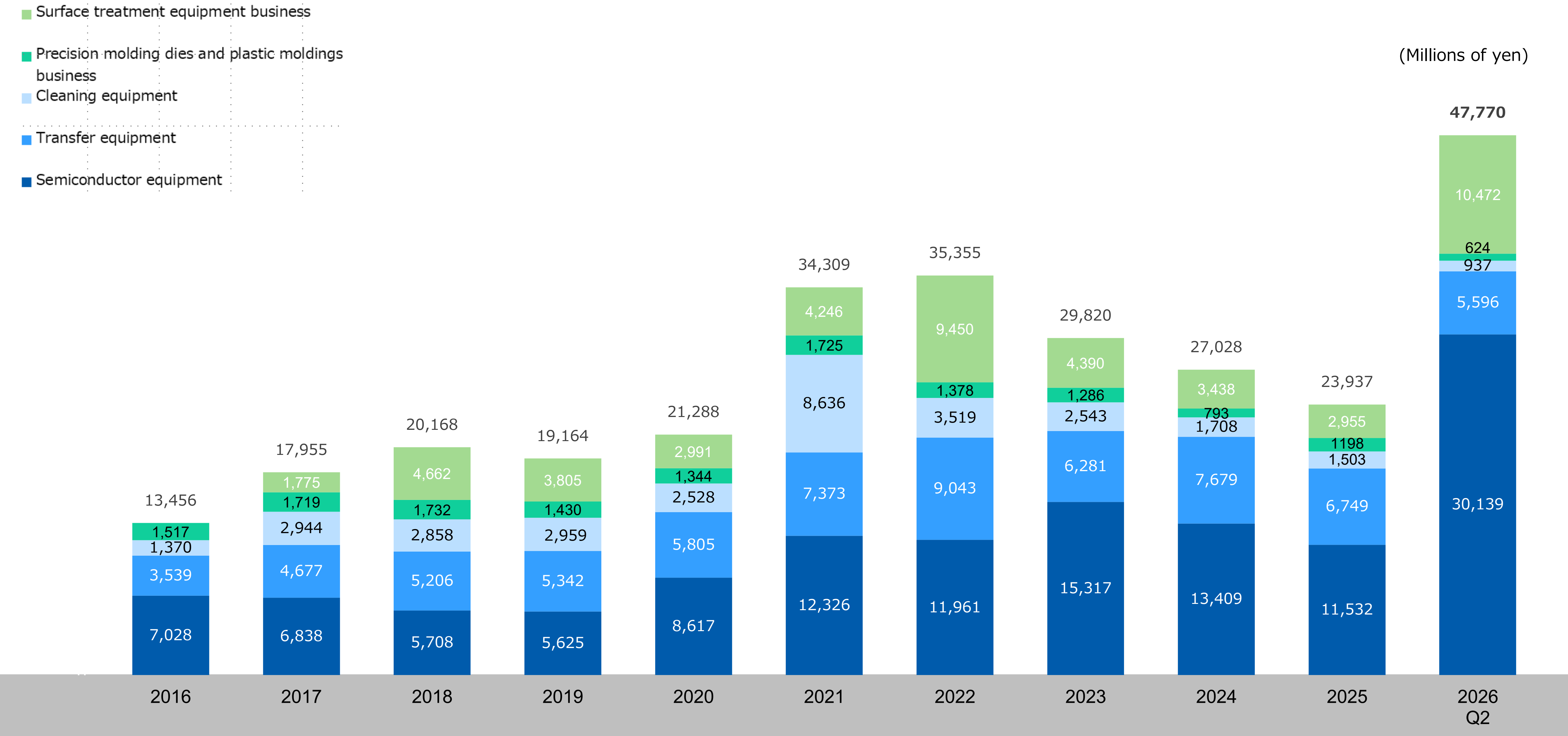

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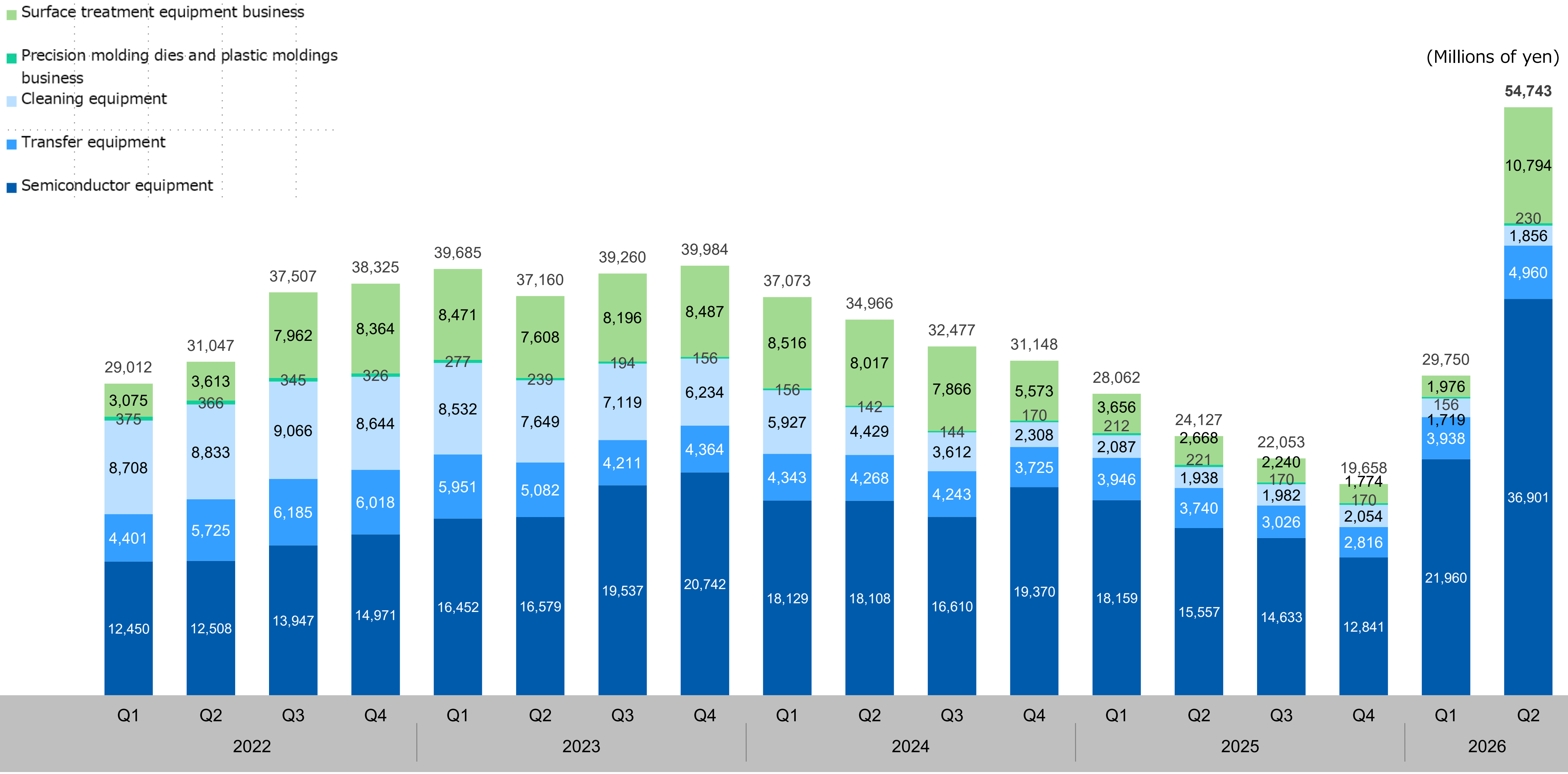
Trend in Order Backlog by Segment(Quarterly)

TAZMO



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3 Business Environment

Business Environment

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- For WLP equipment for advanced packaging, order intake declined quarter on quarter following the large orders received in Q1, while orders for coaters and developers expanded. Future orders will depend largely on market conditions, but we remain optimistic. For equipment for power semiconductors, inquiries are gradually increasing.

- In transfer equipment, inquiries have risen sharply and order intake has increased. Despite challenges such as longer lead times for materials and responding to individual customer requirements, we are strengthening our domestic and overseas supply chains.

- For PLP equipment for advanced packaging, inquiries are increasing for the coating, debonding and cleaning processes we have long worked on. The inquiries vary in scale, and we are working to secure them reliably while expecting further market expansion.

- Inquiries for slurry supply equipment are increasing, and we expect further orders going forward. For wafer cleaning equipment, new projects remain limited and we expect recovery to take time.

- In surface treatment equipment, orders expanded for both wet processing equipment centered on plating and substrate transfer equipment. Given the very strong conditions in this market, we remain optimistic going forward.

4 Appendix

Company Profile and Business Overview

TAZMO

TAZMO is a global manufacturer that has kept pace with customers and changing times for half a century. Nearly 80% of net sales come from semiconductor-related business (Process Equipment).

[Company profile as of June 30, 2026]

Group employees
Consolidated, as of June 30, 2026
1,224

Founded
Established in 1972
54th year

Number of sites
11 in Japan + 12 overseas
23 sites

Affiliated subsidiaries
Japan and overseas total
14 companies

[Full-year results, fiscal year ended December 2025]

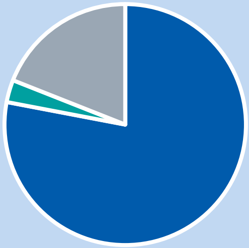
Net sales
FY ended Dec. 2025
35.42 billion yen

Operating profit
FY ended Dec. 2025
4.76 billion yen

Operating margin
FY ended Dec. 2025
13.5%

ROE
FY ended Dec. 2025
14.0%

Net sales by segment
FY ended Dec. 2025

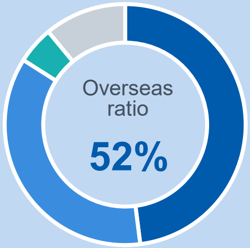


Process Equipment	78%
Molds & Resin	3%
Surface Treatment	19%

Process Equipment net sales breakdown
FY ended Dec. 2025

Semiconductor equipment	51%
Transfer equipment	22%
Cleaning equipment	5%

Net sales by region
FY ended Dec. 2025



Japan	48%
Taiwan	36%
China	5%
Others	11%

Business Evolution and Trend in Equipment Shipments

TAZMO

Founded in the 1980s in semiconductor production equipment. From the late 1990s through the 2000s, FPD equipment accounted for the bulk of shipments. The company then shifted to a semiconductor equipment-centered strategy, and has since expanded into the power semiconductor and advanced packaging markets.

(1) Founding to the 1990s

Entered the semiconductor production equipment business
Accumulated wet process and transfer technologies

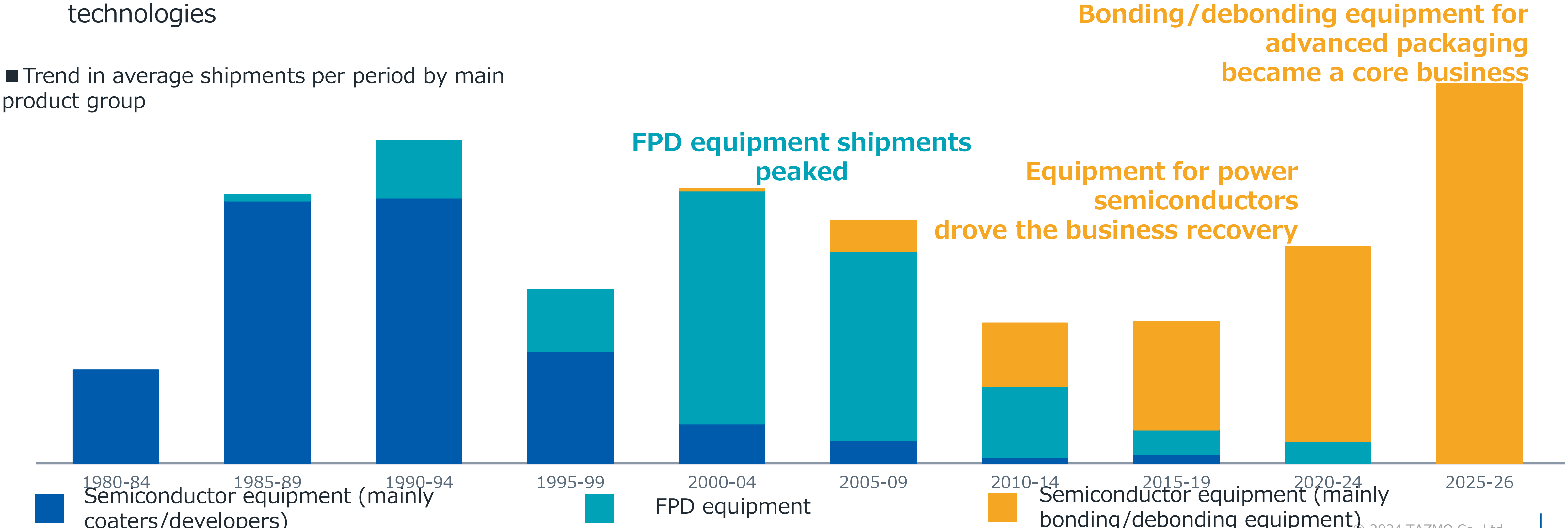
(2) 2000s

FPD equipment became a core
Peaked in the mid-2000s

(3) 2010s to present

From FPD to power semiconductors and advanced packaging, the core business has shifted

■Trend in average shipments per period by main product group



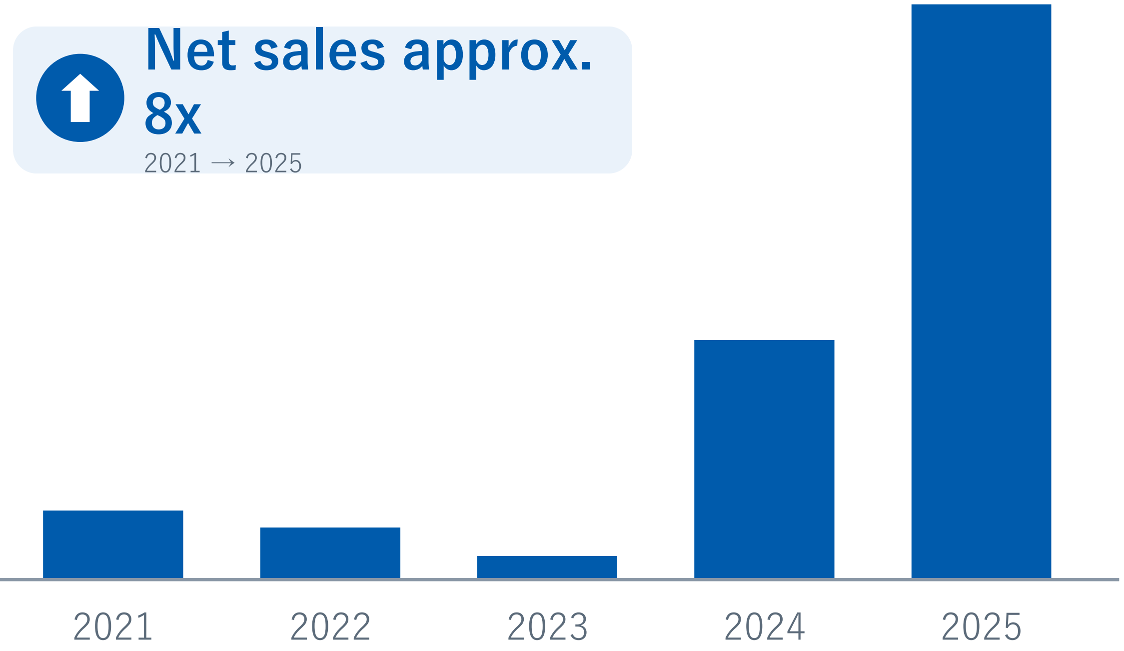
*Shipments for 2025-26 include forecast figures for the fiscal year ending December 202

AI-driven expansion of the logic semiconductor market has significantly grown sales of TAZMO's advanced packaging equipment. TAZMO equipment is used in logic semiconductor manufacturing, where technical requirements keep rising.

■Market size comparison: logic vs. power semiconductors

Source: WSTS (2021-2025 actual; 2026 is the 2026 spring forecast, June 2026).
*Discretes is a category centered on power semiconductors.
*Unit: US$100 million

■TAZMO advanced packaging equipment: net sales trend



Trend in Net sales by Conventional Segment(Quarter)

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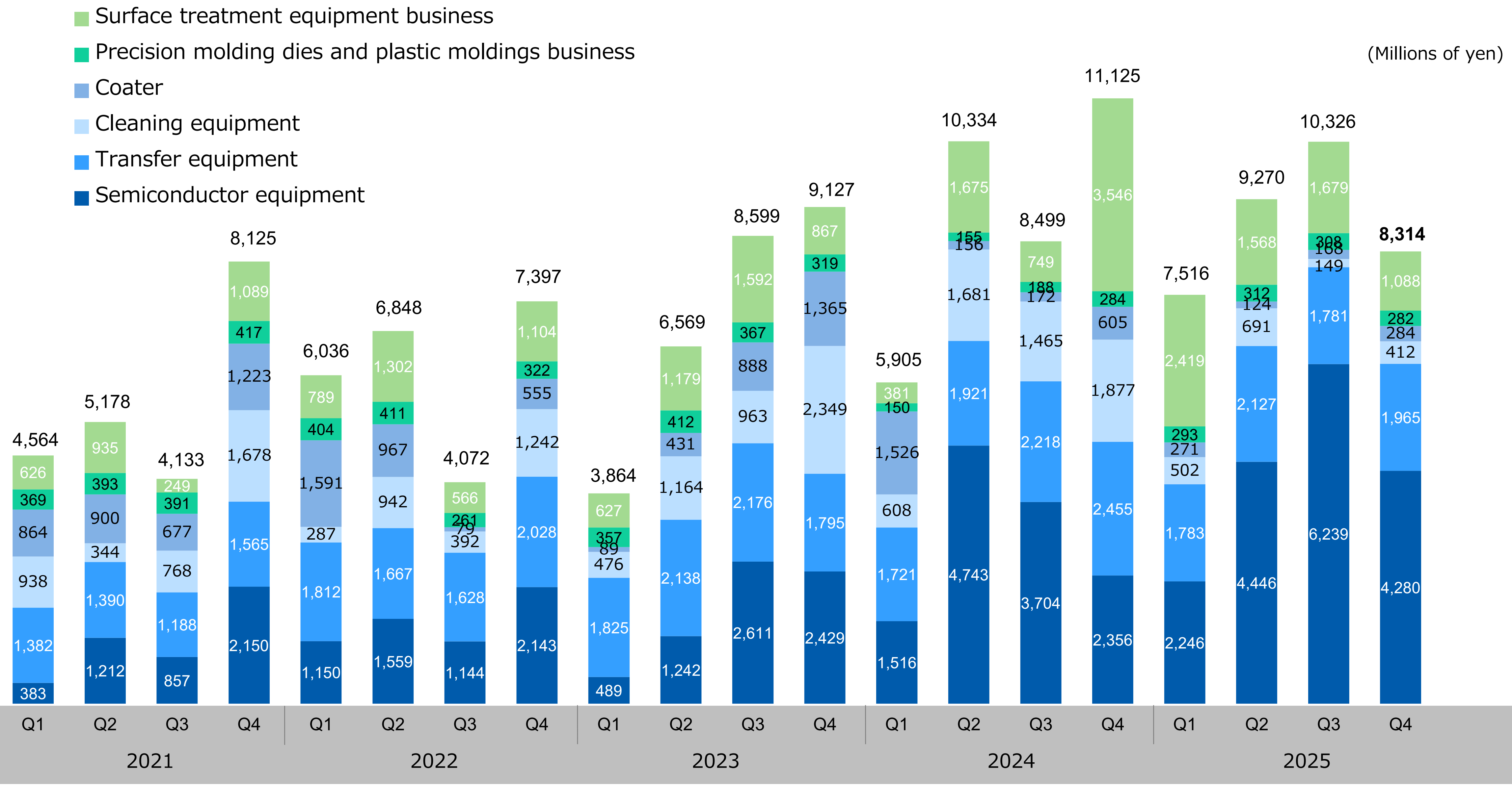
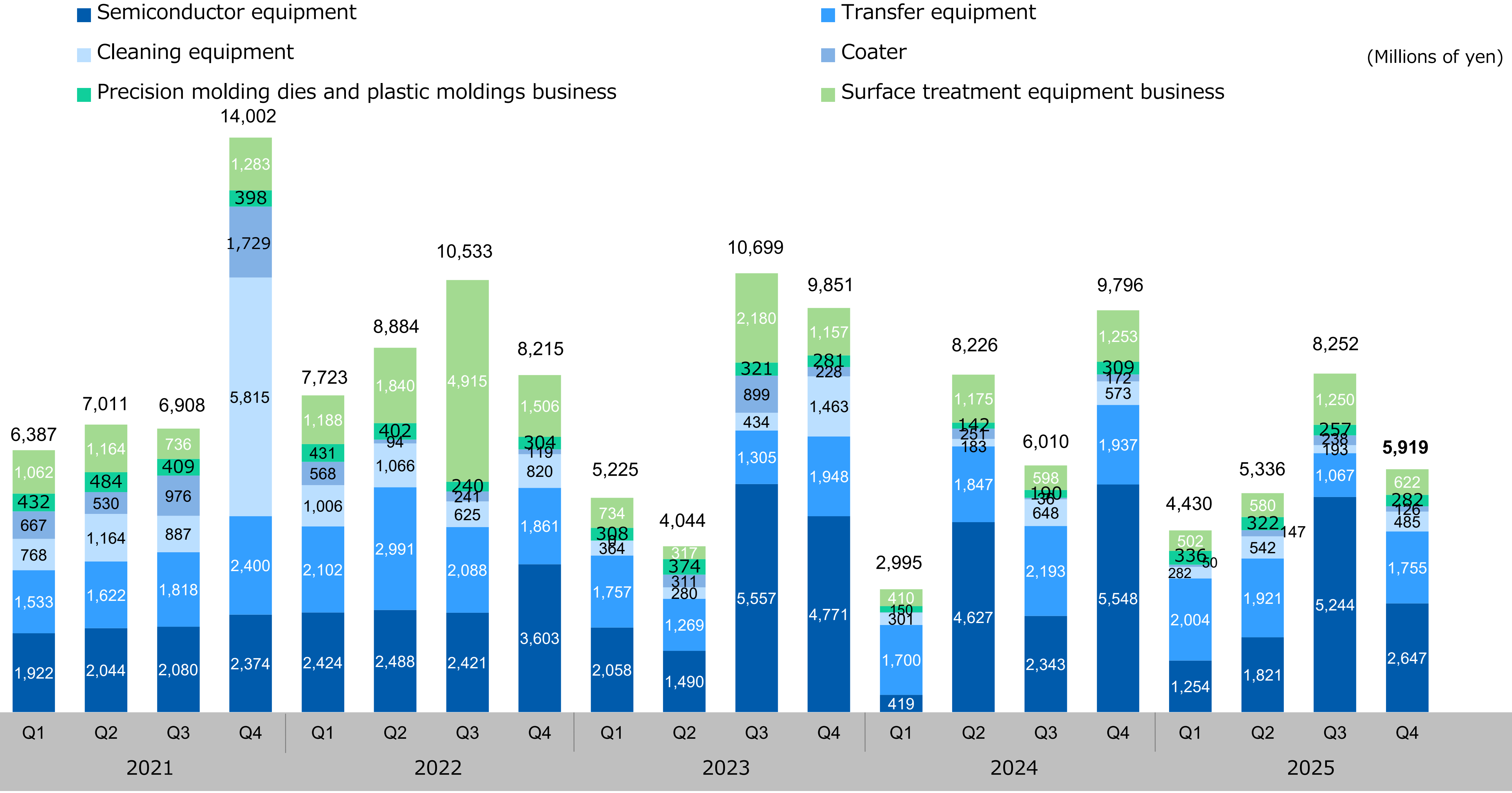


Trend in Sales Orders by Conventional Segment(Quarter)

TAZMO



Trend in Order Backlog by Conventional Segment

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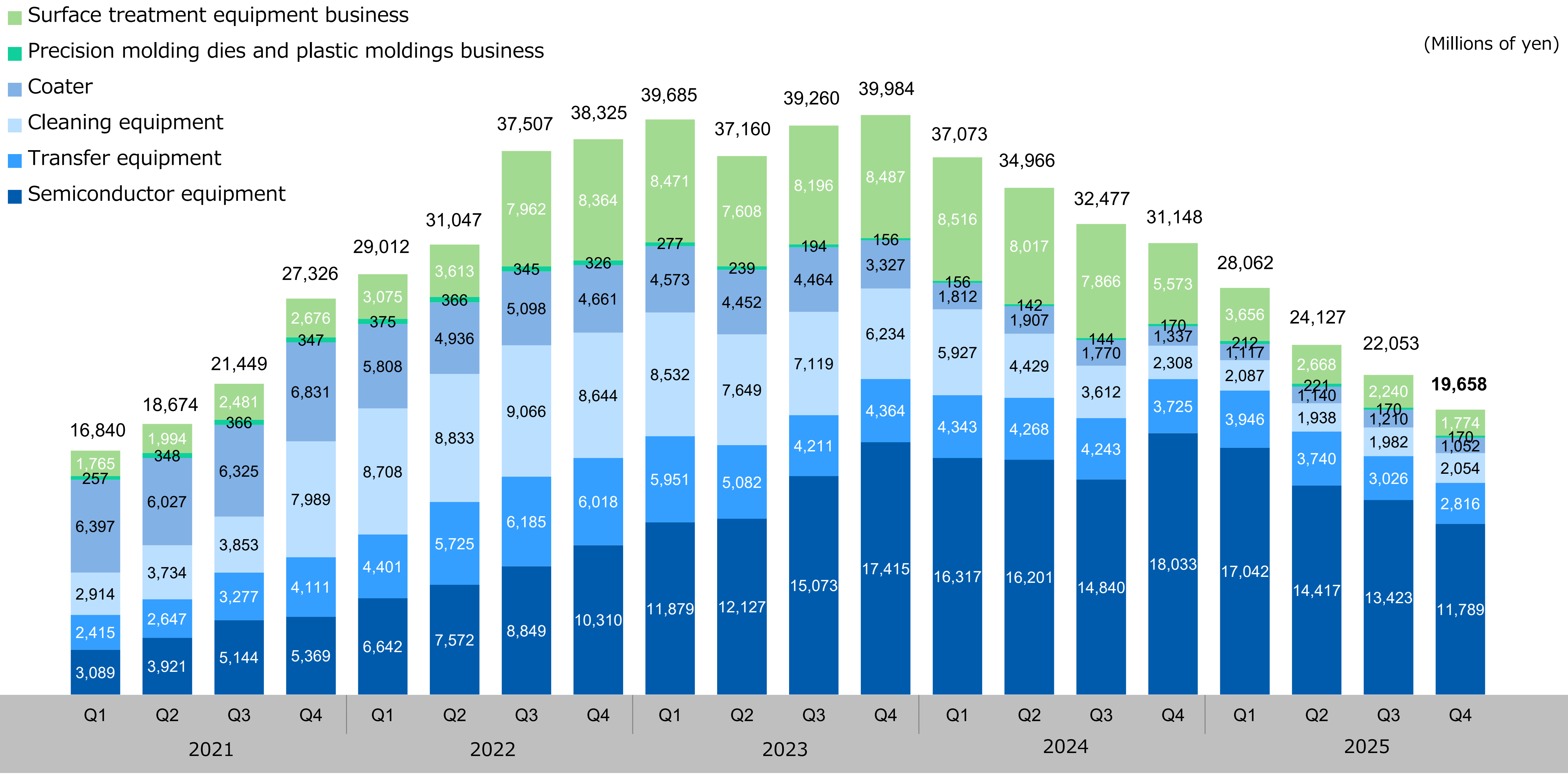
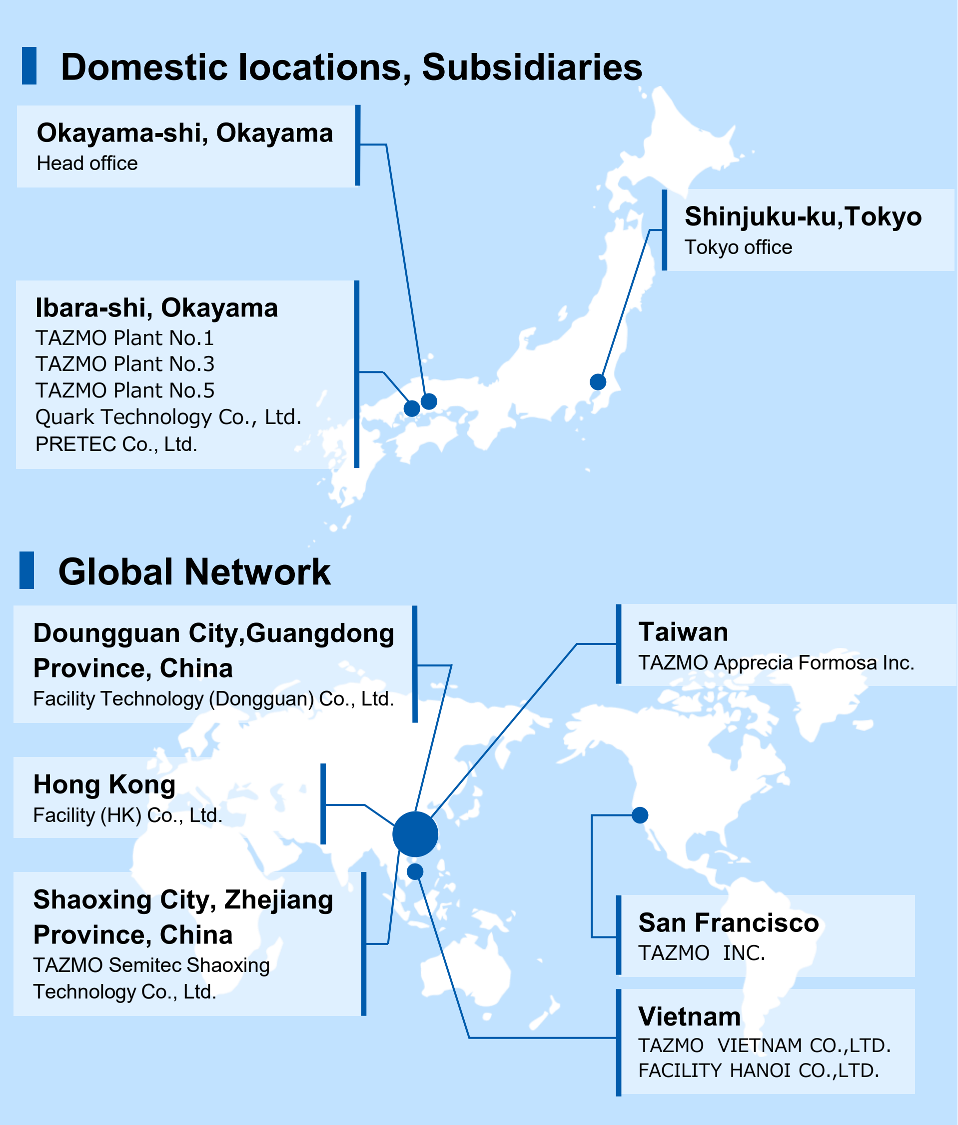


Company Info

TAZMO

(as of June 30, 2026)

Company name	TAZMO Co., Ltd.
Established	February 26, 1972
Head office	5311, Haga, Kita-ku, Okayama-shi, Okayama 701-1221, Japan
Capital	3,556,890,682 yen
Total number of issued shares	14,842,354
Number of shareholders	6,279
Number of employees	Non-consolidated 481 Consolidated 1,224
Business content	Development, Manufacturing and Sales of Semiconductor Manufacturing Equipment, Clean Transfer System, UV Laser Equipment, Plating Equipment, Mold・Resin Molding, Plating/Circuit formation Equipment for PCB



Milestones

TAZMO

1972
- TAZMO Co., Ltd. is incorporated to manufacture and produce electronic components and repair industrial equipment.

1980
- Began production of molding dies, including injection molding dies.
- Completed development of Fully-automated Photo Resist Coater; production and sales started.

1989
- Developed TFT Full-color filter manufacturing system; production and sales started.

1990
- Constructed new head office/plant at 6186 Kinoko-Cho, Ibara, Okayama
- Developed and produced Ultra Compact Transfer System for Super Clean Room.

1994
- Began production and sales of Emboss Carrier Tape.

1995
- Began production of injection Molding Products.

2001
- Developed “CS13” series Photo Resist Coater specialized for a thicker film application; production and sales started.

2004
- Listed on the JASDAQ market.

2008
- Established TAZMO VIETNAM CO., LTD. a consolidated subsidiary, in Ho Chi Minh City, Vietnam.

2009
- Developed 10th generation compatible full-color filter manufacturing system; production and sales started.
- Concluded a license agreement with 3M(USA) for semiconductor manufacturing equipment.

2013
- Apprecia Technology Inc. became our wholly owned subsidiary company.
- VIETNAM CO., LTD. Constructed new factory at Long Hau Industrial Park in Long An Province, Vietnam.

2017
- Facility Co., Ltd. and Quark Technology Co., Ltd. became our wholly owned subsidiary company.

2018
- Listed on the First Section of the Tokyo Stock Exchange

2019
- Constructed a new head office at 5311 Haga Kita-ku, Okayama-shi, Okayama

2020
- Merged with Apprecia Technology Inc.

2022
- TAZMO’s listing transferred to Prime Market in Tokyo Stock Exchange.
- Increased capital to 3,495,400,000 yen through public offering.
- Established TAZMO SEMITEC SHAOXING TECHNOLOGY Co., Ltd. a consolidated subsidiary, in Zhejiang Shaoxing, China.

Semiconductor Manufacturing Equipment Business Unit

Bonder / Debonder

- For Advanced Packaging(WLP *1／PLP *2)
- For Power Semiconductors

We develop, design, manufacture, and sell temporary bonding and debonding systems that enable wafer thinning, an essential process for the production of high-performance chips.By bonding wafers to glass carrier substrates, our systems allow wafer thinning while preventing damage to the wafers.

Coater / Developer

Leveraging the expertise gained through the development and manufacturing of FPD production equipment, we enable uniform chemical coating and precise circuit formation by selectively removing only the exposed areas during the development process.

*1 WLP:Wafer-Level Packaging
*2 PLP :Panel-Level Packaging

Transfer Business Unit

- For Semiconductor Equipment Manufacturers
  (Wafers, Masks, and Related Components)

Cleaner Business Unit

We develop, design, manufacture, and sell single-wafer cleaning systems for wafer manufacturers, as well as slurry supply systems and equipment that recovers and reuses phosphoric acid from waste liquids.

Molding Business

We provide precision molds and resin molded products for connector manufacturers.

Surface Treatment Business

We provide plating systems for printed circuit boards used in semiconductor packages and electronic control systems for automobiles and other applications.

Notes

Forward-looking statements with respect to TAZMO's business plan, prospects and other such information are based on information available at the time of publication. Actual performance and results may differ significantly from the business plan described here due to changes in various external and internal factors.

This material takes as its objective the provision of information regarding the management policy, plans, and financial situation of TAZMO to shareholders, investors and other visitors. It constitutes neither an offer nor a solicitation to purchase or sell TAZMO stock.

Contact

Finance Department,
Investor Relations Section
TAZMO CO., LTD.

keiki@tazmo.co.jp